

500mW, 2.4V - 7.5V Surface Mount Zener Diode

FEATURES

- Wide Zener voltage range selection: 2.4V to 75V
- V_Z tolerance selection of $\pm 5\%$
- Hermetically sealed glass
- RoHS Compliant

APPLICATIONS

- Low voltage stabilizers or voltage references
- Adapters
- On-board DC/DC converter

MECHANICAL DATA

- Case: MMELF
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Polarity: Indicated by cathode band
- Weight: 30.60mg (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
V_Z	2.4 - 75	V
Test current I_{ZT}	2.5 - 5.0	mA
P_D	500	mW
V_F at $I_F = 10\text{mA}$	1	V
$T_{J \text{ Max}}$	175	$^{\circ}\text{C}$
Package	MMELF	
Configuration	Single die	



MMELF



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	VALUE	UNIT
Forward voltage @ $I_F = 10\text{mA}$	V_F	1	V
Power dissipation	P_D	500	mW
Junction temperature range	T_J	-65 to +175	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-65 to +175	$^{\circ}\text{C}$

THERMAL PERFORMANCE

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	300	$^{\circ}\text{C/W}$

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PART NUMBER	ZENER VOLTAGE			TEST CURRENT	REGULAR IMPEDANCE		TEST CURRENT	LEAKAGE CURRENT	
	$V_Z @ I_{ZT}$			I_{ZT}	$Z_{ZT} @ I_{ZT}$	$Z_{ZK} @ I_{ZK}$	I_{ZK}	$I_R @ V_R$	
	V			mA	Ω	Ω	mA	μA	V
	Min	Nom	Max		Max	Max		Max	
BZV55C2V4	2.28	2.4	2.56	5	85	600	1.0	50	1.0
BZV55C2V7	2.51	2.7	2.89	5	85	600	1.0	10	1.0
BZV55C3V0	2.8	3.0	3.2	5	85	600	1.0	4	1.0
BZV55C3V3	3.1	3.3	3.5	5	85	600	1.0	2	1.0
BZV55C3V6	3.4	3.6	3.8	5	85	600	1.0	2	1.0
BZV55C3V9	3.7	3.9	4.1	5	85	600	1.0	2	1.0
BZV55C4V3	4.0	4.3	4.6	5	75	600	1.0	1	1.0
BZV55C4V7	4.4	4.7	5.0	5	60	600	1.0	0.5	1.0
BZV55C5V1	4.8	5.1	5.4	5	35	550	1.0	0.1	1.0
BZV55C5V6	5.2	5.6	6.0	5	25	450	1.0	0.1	1.0
BZV55C6V2	5.8	6.2	6.6	5	10	200	1.0	0.1	2.0
BZV55C6V8	6.4	6.8	7.2	5	8	150	1.0	0.1	3.0
BZV55C7V5	7.0	7.5	7.9	5	7	50	1.0	0.1	5.0
BZV55C8V2	7.7	8.2	8.7	5	7	50	1.0	0.1	6.2
BZV55C9V1	8.5	9.1	9.6	5	10	50	1.0	0.1	6.8
BZV55C10	9.4	10	10.6	5	15	70	1.0	0.1	7.5
BZV55C11	10.4	11	11.6	5	20	70	1.0	0.1	8.2
BZV55C12	11.4	12	12.7	5	20	90	1.0	0.1	9.1
BZV55C13	12.4	13	14.1	5	26	110	1.0	0.1	10
BZV55C15	13.8	15	15.6	5	30	110	1.0	0.1	11
BZV55C16	15.3	16	17.1	5	40	170	1.0	0.1	12
BZV55C18	16.8	18	19.1	5	50	170	1.0	0.1	13
BZV55C20	18.8	20	21.1	5	55	220	1.0	0.1	15
BZV55C22	20.8	22	23.3	5	55	220	1.0	0.1	16
BZV55C24	22.8	24	25.6	5	80	220	1.0	0.1	18
BZV55C27	25.1	27	28.9	5	80	220	1.0	0.1	20
BZV55C30	28	30	32	5	80	220	1.0	0.1	22
BZV55C33	31	33	35	5	80	220	1.0	0.1	24
BZV55C36	34	36	38	5	80	220	1.0	0.1	27
BZV55C39	37	39	41	2.5	90	500	0.5	0.1	28
BZV55C43	40	43	46	2.5	90	600	0.5	0.1	32
BZV55C47	44	47	50	2.5	110	700	0.5	0.1	35
BZV55C51	48	51	54	2.5	125	700	0.5	0.1	38
BZV55C56	52	56	60	2.5	135	1,000	0.5	0.1	42
BZV55C62	58	62	66	2.5	150	1,000	0.5	0.1	47
BZV55C68	64	68	72	2.5	160	1,000	0.5	0.1	51
BZV55C75	70	75	80	2.5	170	1,000	0.5	0.1	56

Notes:

1. The Zener voltage (V_Z) is tested under pulse condition of 30ms.
2. The device numbers listed have a standard tolerance on the normal Zener voltage of $\pm 5\%$.
3. For detailed information on price, availability and delivery of normal Zener voltages between the voltages shown and tighter voltage tolerances, contact your nearest Taiwan Semiconductor representative.
4. The Zener impedance is derived from the 60-cycle AC voltage, which results when an AC current having an rms value equal to 10% of the DC Zener current (I_{ZT} or I_{ZK}) is superimposed to I_{ZT} or I_{ZK} .

ORDERING INFORMATION		
ORDERING CODE⁽¹⁾⁽²⁾	PACKAGE	PACKING
BZV55Cx L0	MMELF	10,000 / 13" Tape & Reel
BZV55Cx L0G	MMELF	10,000 / 13" Tape & Reel

Notes:

1. "x" defines voltage from 2.4V (BZV55C2V4) to 75V (BZV55C75)
2. Above ordering codes L0/L0G refer to physically identical parts without any differences

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Power Dissipation VS. Ambient Temperature

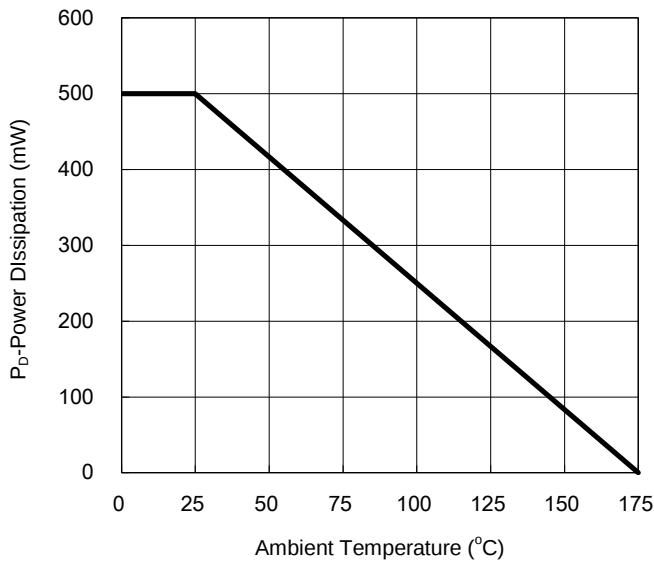


Fig.2 Total Capacitance

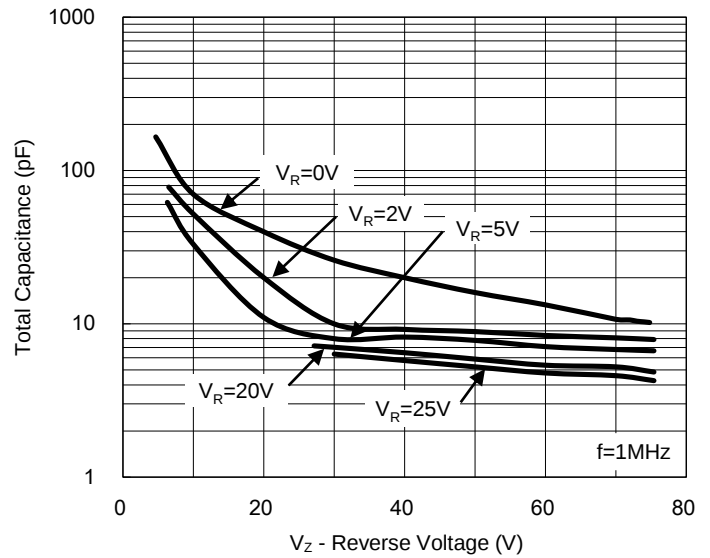


Fig.3 Differential Impedance VS. Zener Voltage

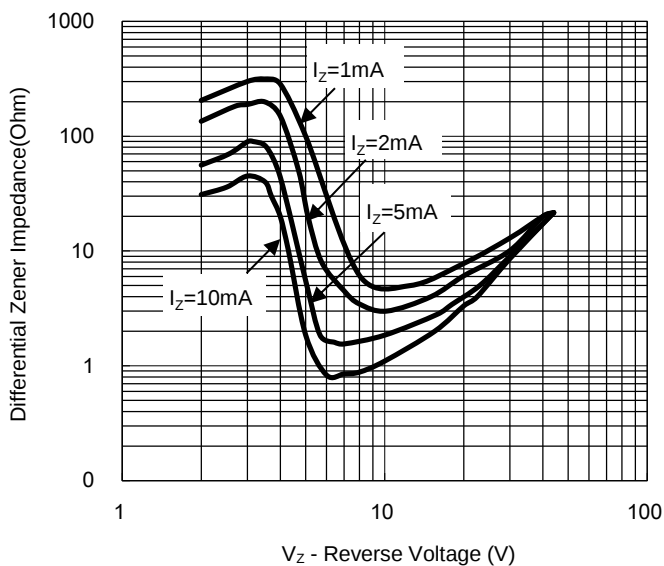
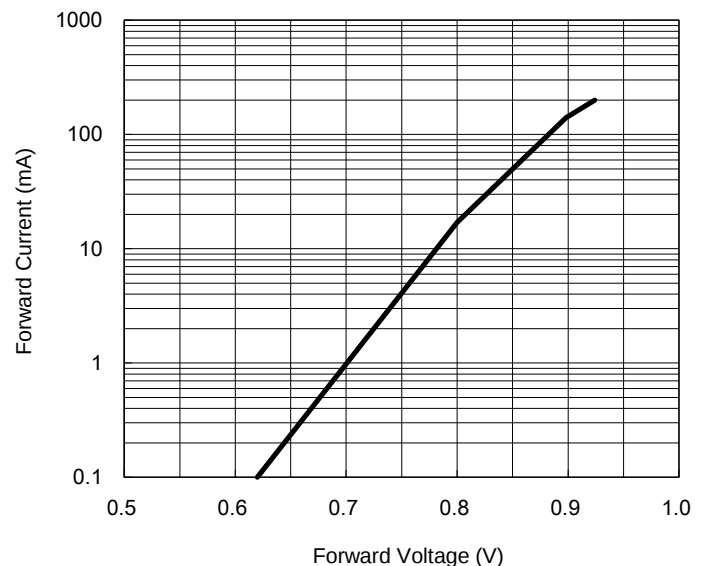
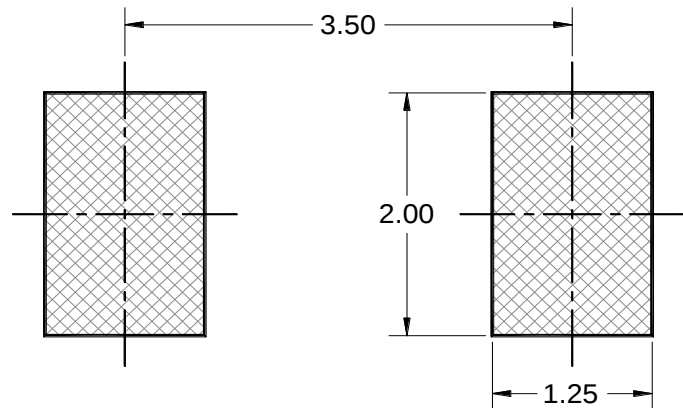
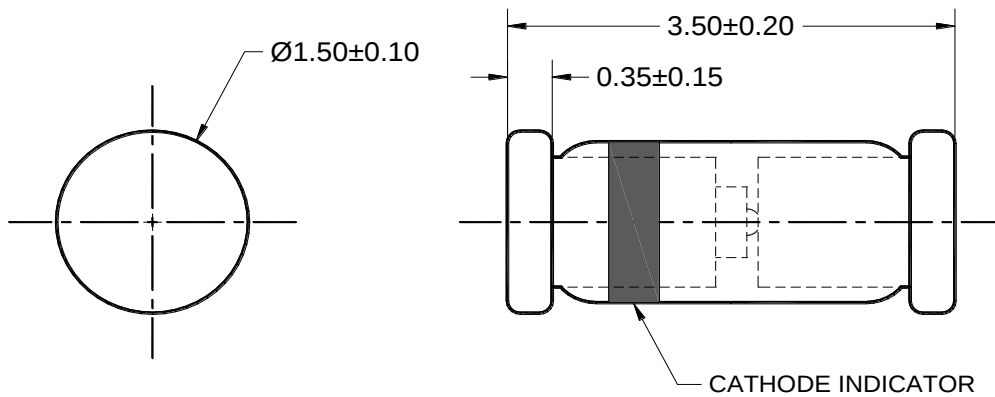


Fig.4 Forward Current VS. Forward Voltage



PACKAGE OUTLINE DIMENSIONS

MMELF



NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC DO-213, VARIATION AA, ISSUE D.
4. DWG NO. REF: HQ2SD07-MMELFG-044 REV A.

SUGGESTED PAD LAYOUT

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